

CKC18C562GCGAC7210

KC-LINK Comm COG, Ceramic, 5600 pF, 2%, 500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1812



Click here for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 1812 |
| L | 4.5mm +/-0.3mm |
| W | 3.2mm +/-0.3mm |
| Т | 1.25mm +/-0.15mm |
| В | 0.6mm +/-0.35mm |

| Packaging Specifications | | |
|--------------------------|--------------------------|--|
| Packaging | T&R, 330mm, Plastic Tape | |
| Packaging Quantity | 4000 | |

| General Information | |
|---------------------|--|
| Series | KC-LINK Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 67 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------------|
| Capacitance | 5600 pF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 2% |
| Voltage DC | 500 VDC |
| Dielectric Withstanding Voltage | 750 VDC |
| Temperature Range | -55/+150°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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